

CHIPCONNECT CABLE ASSEMBLIES

Internal Faceplate-to-Processor Cable Assemblies for Intel® Omni-Path Architecture 100 Series

TE Connectivity's (TE) ChipConnect internal faceplate-to-processor cable assemblies are designed for Intel Omni-Path Architecture (OPA), which can directly transmit signals from the processor to the faceplate. ChipConnect cable assemblies mate directly mate with Intel Xeon® Phi™ processors and Intel Xeon Scalable processors on the board and Intel Omni-Path Internal Faceplate Transition (IFT) connector at the faceplate for 25 Gbps speeds.

These cable assemblies reduce system design costs by eliminating the need to use costlier, lower-loss printed circuit board (PCB) materials. System design is made easier by reducing the complexity of PCB laminates and routing, as well as retimers.

APPLICATIONS

- Data Center & Networking Equipment
  - Servers
  - Routers
  - High Performance Computing (HPC)

ChipConnect Cable Assemblies

Our ChipConnect cable assembly solution is specifically designed to address the overall trend towards internal cabling to reduce PCB cost and optimize system performance. This internal cabling system is offered in multiple configurations that can support applications at 25 Gbps.

MEET LATEST INTEL CPU PROCESSOR DESIGN

- Enable Intel Omni-Path Architecture (OPA) by mating directly with Intel Xeon Phi processors and Intel Xeon Scalable processors on the board and IFT connectors at the faceplate for 25 Gbps speeds

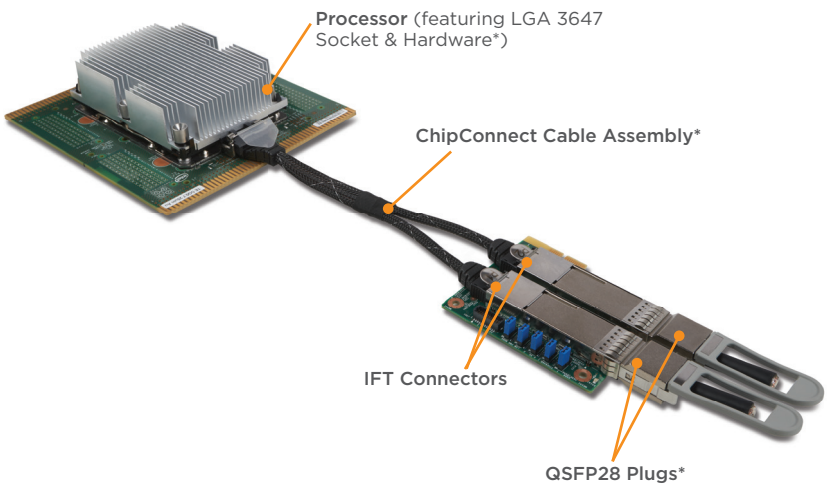
FULL SOLUTION PARTNER

- TE is one of two Intel-qualified suppliers offering these first-generation cable assemblies (100 Series) and is also a development partner for future-generation Intel designs
- In addition to these cable assemblies, we offer the compatible LGA 3647 sockets and hardware required for Intel OPA

CHOOSE YOUR CONFIGURATION

- ChipConnect cable assemblies are available in standard lengths and breakouts, but can be customized for specific applications
- Take advantage of our broad range of high speed solutions such as Sliver internal cabled interconnects and STRADA Whisper board-to-board connectors to create a custom connection on the board or faceplate

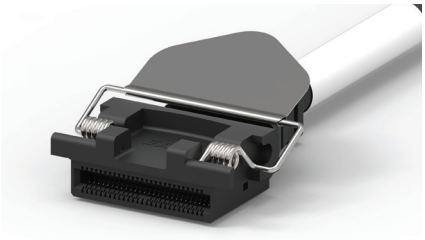
Intel Omni-Path Architecture



*Products offered by TE



Intel Omni-Path Internal Faceplate-to-Processor (IFP) Plug - *mates to IFT connector*



Linear Card Edge (LEC) Receptacle - *mates to Intel processors*

Key Features

- Cables provide 4x and 8x high speed data transmission lanes
- Straight and right-angle (left/right exit) Linear Edge Connector (LEC) cable plugs to accommodate cable routing
- LEC receptacle offered in A (mate to LGA 3647 socket P1) and B (mate to LGA 3647 socket P0) versions
- Bail latch with pull tab on LEC plug and spring latching on IFP plug provides secure connections
- Mid-board copper chip-to-I/O interconnect reduces host system board trace lengths and PCB cost
- Assemblies utilize TE bulk cable 30 AWG 85 Ohms TurboTwin 25 Gbps primary pair cable

Specifications

- Product spec: 108-130015

PRODUCT OFFERING

IFP Style	Number of Ports	LEC Configuration	IFP Configuration	Assembly Length (mm)	Breakout Length (mm)	Part Number
A	2	Straight	Flat	142	75	2821719-3
				208	104.5	2821719-1
				405	104.5	2821719-2
				460	104.5	2821719-4
			Inverted	208	104.5	2821720-1
				405	104.5	2821720-2
B	1	Straight	Flat	150	N/A	2821721-1
			Inverted	160	N/A	2821722-1
				205	N/A	2821722-2
				242	N/A	2821722-3
				465	N/A	2821722-4
		Left Angle	Flat	142	N/A	2821723-4
				335	N/A	2821723-1
				371	N/A	2821723-2
				460	N/A	2821723-5
				515	N/A	2821723-3
			Inverted	178	N/A	2821724-1
				235	N/A	2821724-2
				318	N/A	2821724-3
				419	N/A	2821724-4
				439	N/A	2821724-5
				500	N/A	2821724-6
		Right Angle	Flat	142	N/A	2821778-1
				460	N/A	2821778-2
			Inverted	235	N/A	2821725-1
				370	N/A	2821725-2
				500	N/A	2821725-3

Cable lengths exceeding 439mm are not part of our standard offering and have not been qualified by Intel

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